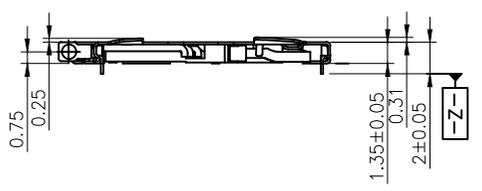
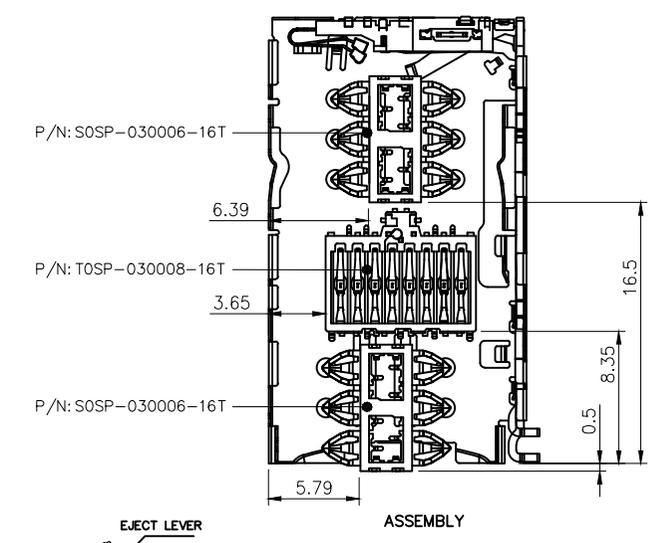
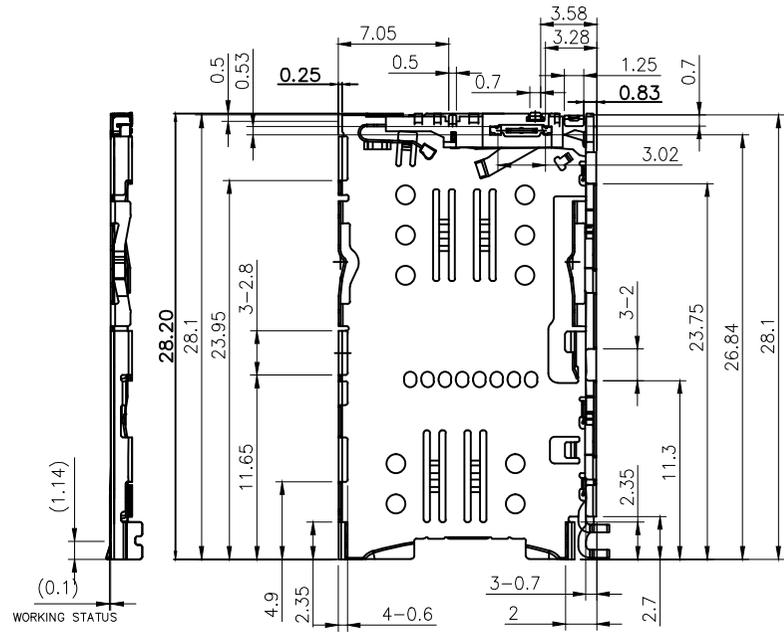
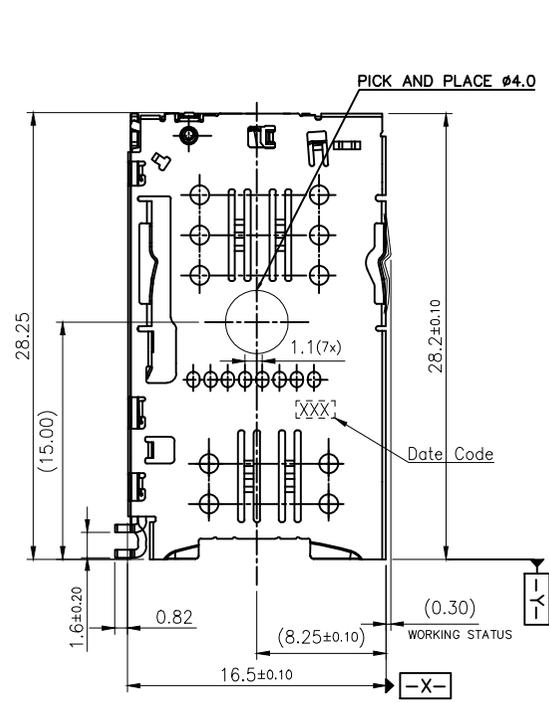
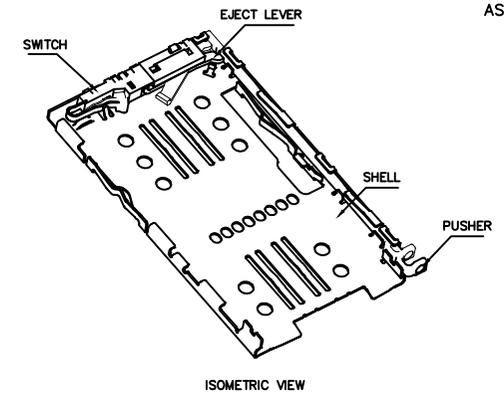
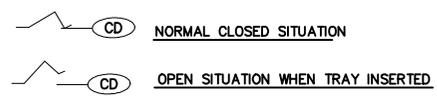


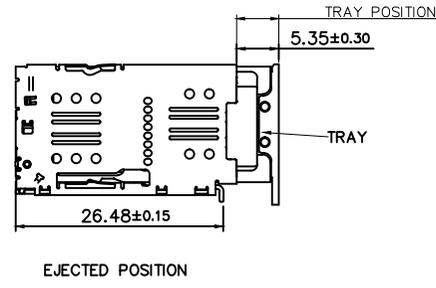
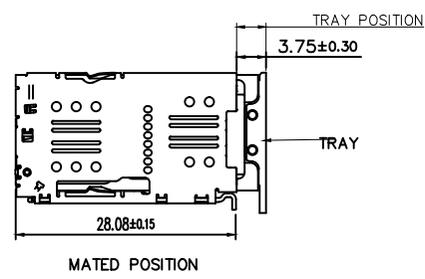
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2019/05/29



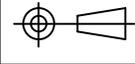
Timing sequence
When tray insert first time, Detect Sw. is activated



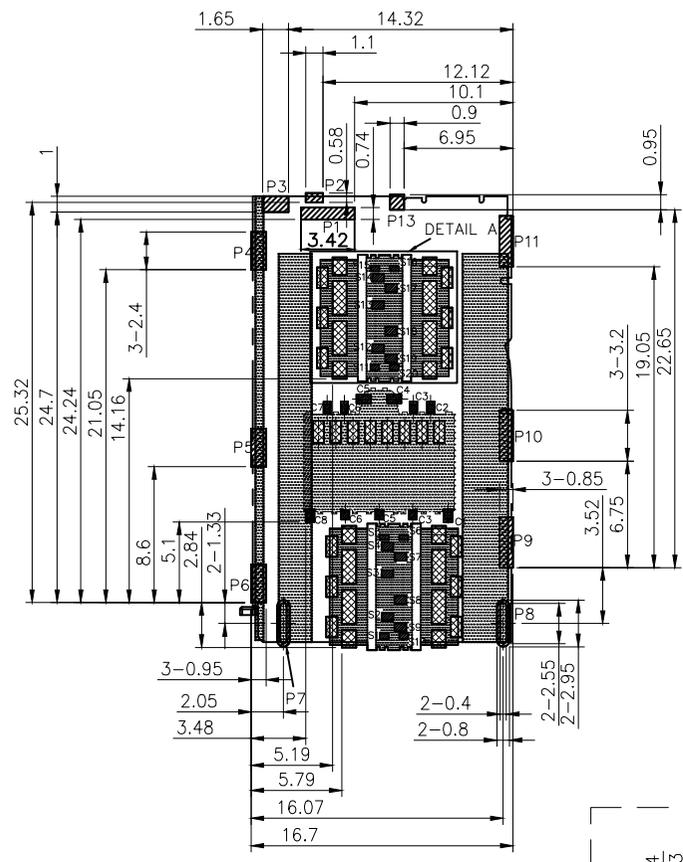
SPECIFICATION
CONTACT RESISTANCE (data) $\leq 100 \text{ m}\Omega$ INITIAL
INSULATION RESISTANCE $\geq 1000 \text{ M}\Omega$
HIGH VOLTAGE RESISTANCE 500 V AC 1 MINUTE
OPERATING VOLTAGE (SELV) 10 V DC
PEAK CURRENT Max.0.5 A
OPERATING TEMPERATURE $-20^\circ\text{C}/+85^\circ\text{C}$
STORAGE TEMPERATURE $-20^\circ\text{C}/+85^\circ\text{C}$
"RoHS" COMPLIANT
MECHANICAL LIFETIME Min.3000 MATING CYCLE
CONTACT FORCE 0.2N
CO-PLANARITY Max.0,08 MM BEFORE REFLOW
Max.0,10 MM AFTER REFLOW



Item	Description	Q'TY	Material	Finished
1	Switch Block	1	LCP	Contact area: Gold plating Under plate: 1.25 um Min Ni
	Detect pin	1	SUS	Solder area: Gold plating Under plate: 1.25 um Min Ni
2	Shell	1	SUS	Contact area: Gold plating Under plate: 1.25 um Min Ni Solder area: Gold plating Under plate: 1.25 um Min Ni
3	Pusher	1	SUS	N/A
4	Eject lever	1	SUS	N/A

GENERAL TOLERANCE		DWG NO.	JYSA0529-001	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	1.35H 板上三选二卡座 分体式	CHKD:	DR:	UNIT	mm
.X±0.35	.x'±2'						
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM135-176	Date	2019/05/29		
.XXX±0.15	.xxx'±0.5'	 Shenzhen JYSCONN Electronics Co., LTD.					
SHEET	1/2						

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2019/05/29



μSD Block Pin Definition

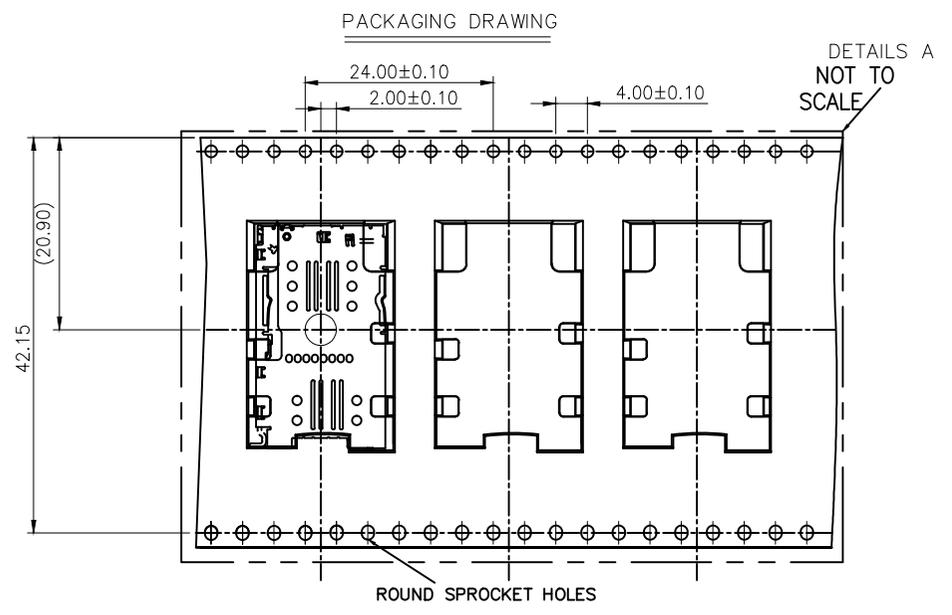
Pin	NAME
C1	DAT2
C2	CD/DAT3
C3	CMD
C4	V _{DD}
C5	CLK
C6	V _{SS}
C7	DAT0
C8	DAT1

SIM Block Pin Definition

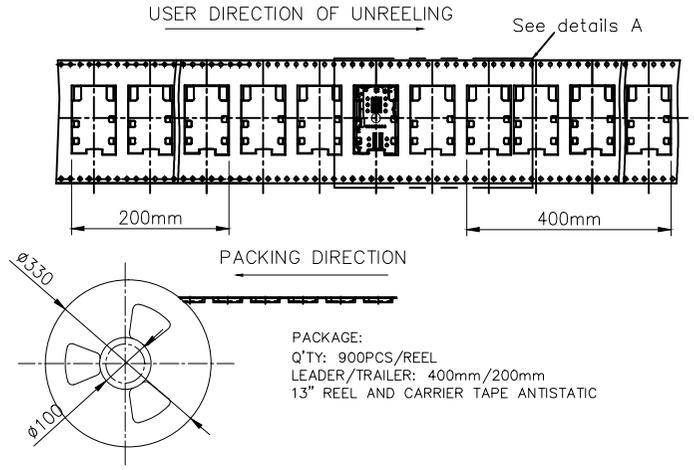
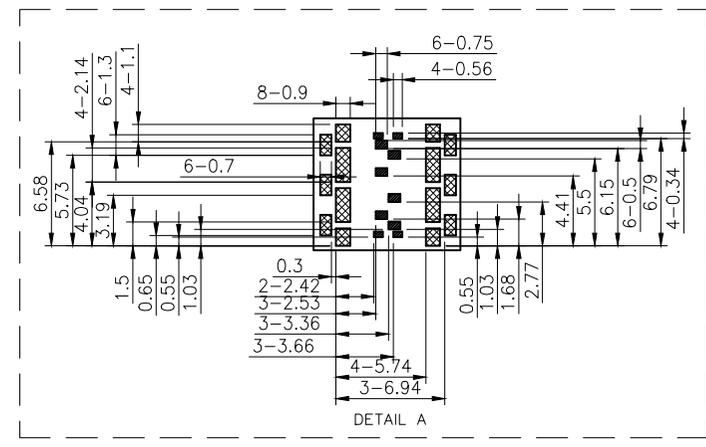
NANO SIM	NAME
S1,S11,S2,S12	V _{CC}
S3,S13	RST
S4,S5,S14,S15	CLK
S6,S7,S16,S17	I/O
S8,S18	V _{PP}
S9,S10,S19,S20	GND

Holder Pin Definition

Pin	NAME
P1~P12	Ground
P13	Detect Switch



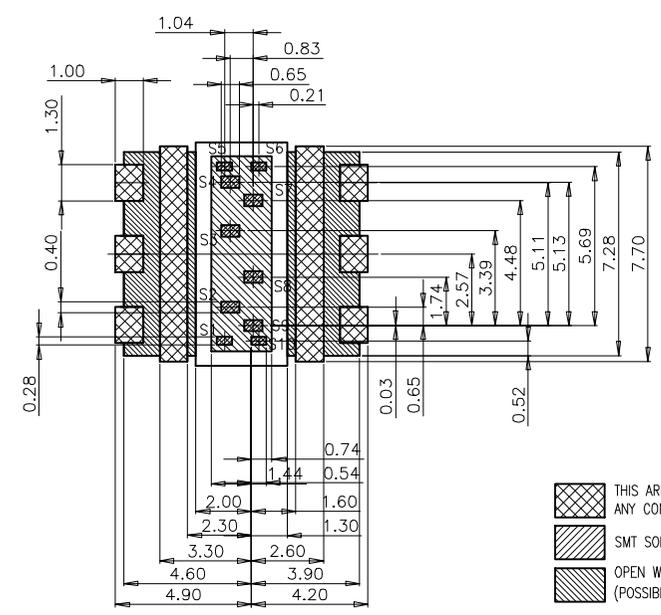
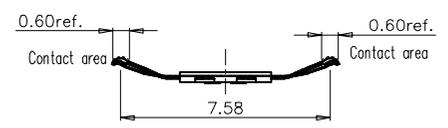
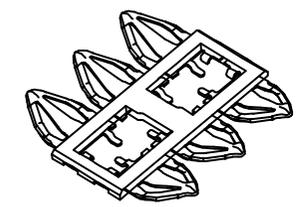
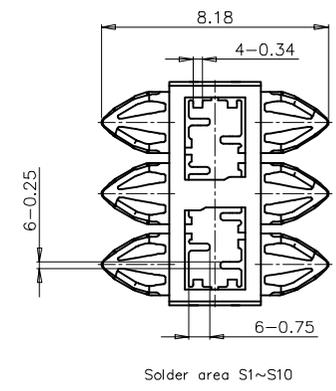
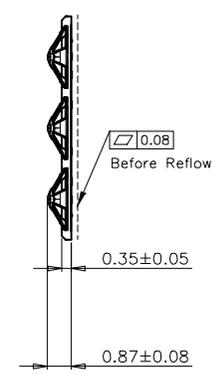
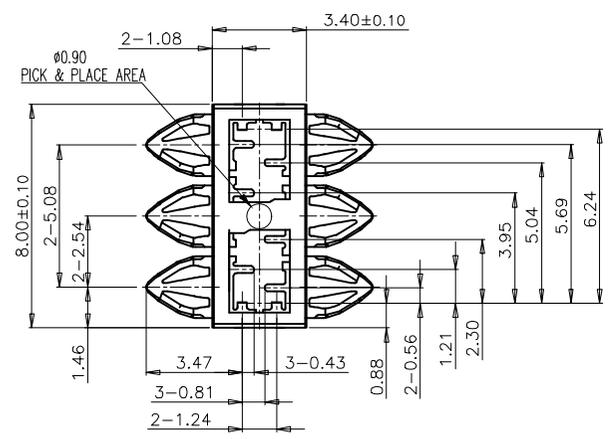
Recommend PCB Layout
 Recommend tolerance: ±0.05
 Recommend Stencil Thickness: 0.10



- Soldering Pad area
- Open wire restricted area (possibility touch of components on PCB)
- Connector outline
- Open wire & copper restricted area
 - 1.Touch area of contact tips, No electrical function and only for mechanical function
 - 2.No first PCB-Layer circuits in the area
- None solder Pad area
 - 1.Touch area of contact tips, No electrical function and only for mechanical function
 - 2.Don't brush Tin pasted on the area during SMT process

GENERAL TOLERANCE		DWG NO.	JYSA0529-001	APPD:	WIND	Scale	1:1
X.±0.45	x.±5'	Title	1.35H 板上三选二卡座 分体式	CHKD:		UNIT	mm
X.±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM135-176	Date	2019/05/29		
.XXX±0.15	.xxx'±0.5'						
SHEET	2/2			JYSCONN Shenzhen JYSCONN Electronics Co., LTD.			

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2019/05/29



- THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES
- SMT SOLDER AREA
- OPEN WIRE RESTRICTED AREA (POSSIBLY TOUCH OF COMPONENTS ON PCB)

RECOMMEND PCB LAYOUT (TOLERANCE ±0.05)

NANO SIM Pin definition

PIN	NAME
S1,S2	Vcc
S3	RST
S4,S5	CLK
S6,S7	I/O
S8	Vpp
S9,S10	GND

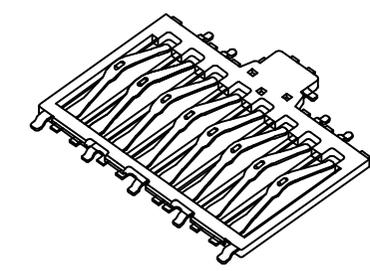
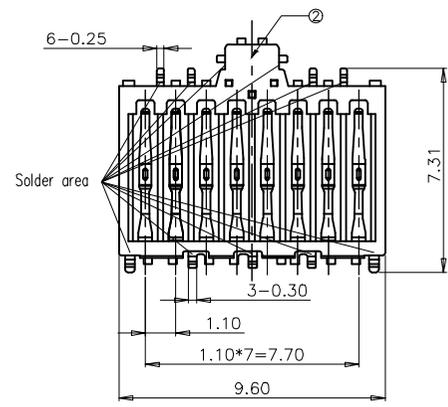
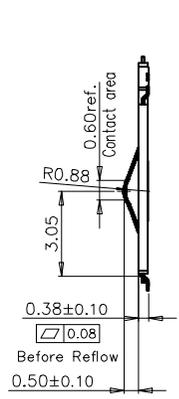
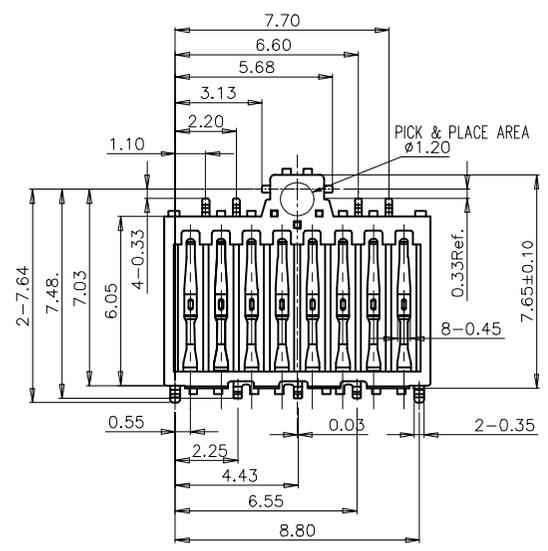
NOTES:

1. MATERIAL:SEE TABLE 1.
2. SPECIALITY:
 - 2.1 Rated current:0.5A Max
 - 2.2 Rated voltage:10V DC
 - 2.3 Contact Resistance:60mΩ MAX
 - 2.4 Insulation Resistance:1000MΩ MIN 500V DC
 - 2.5 Dielectric withstanding voltage: 500V AC 1 MINUTE.
 - 2.6 Solder ability:245±5℃, 5±0.5s.
 - 2.7 Durability:3000 Cycles Min.
 - 2.8 Operating condition:Temperature-20℃~+85℃; Humidity 80% R.H MAX
3. MECHANICAL:
 - 3.1 Contact Force:0.2N Min
4. PLEASE CONTACT KRCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY

②	Housing	1	LCP 6808	COLOUR:BLACK	UL 94V-0
①	Contact	1	NKT-322	Contact area:Plating Au 0.25um min Solder area:Plating Au 0.025um min Under Plating:Ni 1.25um min	T=0.08±0.01mm
NO.	PART NAME	QTY	MATERIAL	DESCRIPTION	REMARK

GENERAL TOLERANCE		DWG NO.	JYSA0909-001	APPD:	WIND	Scale	1:1
X.±0.45	x.±5'	Title	0.3H SIM CARD CONN.	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM030-196	Date	2019/05/29		
.XXX±0.15	.xxx'±0.5'						
SHEET	1/1	JYCONN Electronics Co., LTD.					

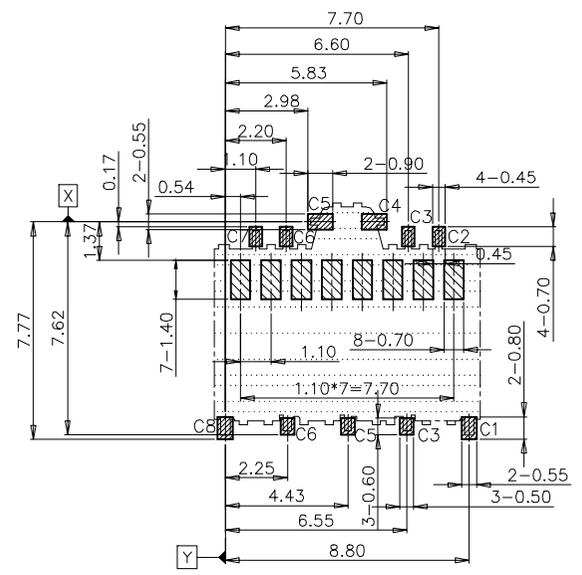
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2019/05/29



μSD Block Pin Definition

PIN	NAME
C1	DATA2
C2	CD/DATA3
C3	CMD
C4	VCD
C5	CLK
C6	Vss2
C7	DATA0
C8	DATA1

- NOTES:
- MATERIAL:SEE TABLE 1.
 - SPECIALITY:
 - Rated current:0.5A Max
 - Rated voltage:10V DC
 - Contact Resistance:60mΩ MAX
 - Insulation Resistance:1000MΩ MIN 500V DC
 - Dielectric withstanding voltage: 500V AC 1 MINUTE.
 - Solder ability:245±5℃, 5±0.5s.
 - Durability:3000 Cycles Min.
 - Operating condition:Temperature-20℃~+85℃, Humidity 80% R.H MAX
 - MECHANICAL:
 - Contact Force:0.2N Min
 - PLEASE CONTACT KRCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY



- Soldering Pad area
- Open wire restricted area (possibly touch of componets on PCB)
- Connector outline
- Pad area(only for mechanical function)
 - Touch area of contact tips, no electrical function and only for mechanical function
 - Don't brush Tin pasted on the area during SMT process.

RECOMMEND PCB LAYOUT (TOLERANCE ±0.05)

②	Housing	1	LCP	COLOUR:BLACK	UL 94V-0
①	Contact	1	COPPER ALLOY	Contact Area: Au 3U"Min, Solder area: Au 1U"Min ;Under plate Ni 50u"Min all over	T=0.08±0.01mm
NO.	PART NAME	QTY	MATERIAL	DESCRIPTION	REMARK

GENERAL TOLERANCE		DWG NO.	JYSA0909-001	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	0.3H Micro SD CARD CONN.	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-TF030-060	Date	2019/05/29		
.XXX±0.15	.xxx'±0.5'						
SHEET	1/1	JYCONN Electronics Co., LTD.					